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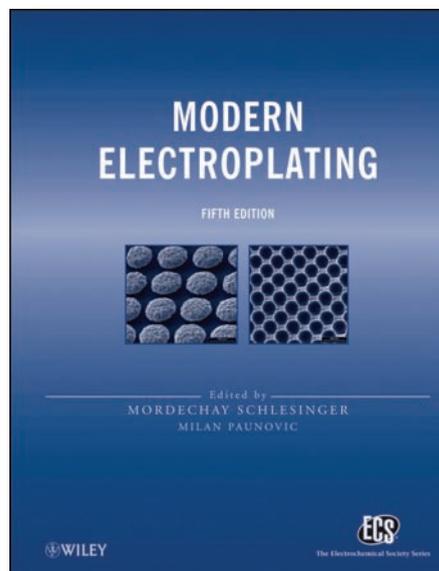
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About the Editor

MORDECHAY SCHLESINGER, PhD, is a professor in the Department of Physics at the University of Windsor, Ontario, Canada. He has published over 120 research papers, holds four patents, and has served as associate editor for the Journal of The Electrochemical Society, *Electrochemical and Solid-State Letters*, and as coeditor of the *Canadian Journal of Physics*. Schlesinger is coauthor, with Milan Paunovic, of the first and second editions of *Fundamentals of Electrochemical Deposition* and the previous edition of *Modern Electroplating* (both by Wiley).

MILAN PAUNOVIC, PhD, had, until his recent retirement, worked on electrochemical metal deposition for over four decades, most recently in the Electrodeposition Technology Department at IBM's T. J. Watson Research Center, and previously at the University of Pennsylvania, Reynolds Metals, Kollmorgen, and Intel. In addition to coauthoring, with Mordechay Schlesinger, the first and second editions of *Fundamentals of Electrochemical Deposition* and the previous edition of *Modern Electroplating*, Dr. Paunovic has edited symposia proceedings for The Electrochemical Society, published forty-one research papers, and holds seven patents.

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